

performance. Optional methods to cover the silicon die enhance thermal performance of the package.

IN THE CLAIMS

Claims 1, 2, and 5 should be replaced with:

1. (amended) A packaged integrated circuit device comprising:

a substrate having a recessed central region surrounded by a raised perimeter, the recessed central region and the perimeter being formed together from the same material, the recessed central region having a plurality of contacts for providing electrical connection from conductors external to the substrate to an integrated circuit device; and

an integrated circuit device formed with contacts on a top surface, flipped, and placed against the recessed central region of the substrate such that the contacts of the integrated circuit device meet the contacts of the recessed central region of the substrate.

2. (amended) The packaged integrated circuit device of Claim 1 wherein the contacts of the recessed central region of the substrate are electrically connected to solder balls on an external surface of the packaged integrated circuit device.

5. (amended) The packaged integrated circuit device of Claim 1 wherein the contacts of the recessed central region of the substrate comprise solder bumps.